

Micro SIDELED® Enhanced optical Power LED (ATON®)

LW Y87C



Besondere Merkmale

- **Gehäusotyp:** weißes SMT Gehäuse
- **Besonderheit des Bauteils:** kleine Bauform mit extrem breiter Abstrahlcharakteristik; ideal für Hinterleuchtungen und Einkopplungen in Lichtleiter
- **Farbort:** $x = 0,33$, $y = 0,33$ nach CIE 1931 (weiß)
- **typische Farbtemperatur:** 5600 K
- **Farbwiedergabeindex:** 80
- **Abstrahlwinkel:** Lambertischer Strahler (120°)
- **Technologie:** InGaN
- **optischer Wirkungsgrad:** 10 lm/W
- **Gruppierungsparameter:** Lichtstärke, Farbort
- **Verarbeitungsmethode:** für alle SMT-Bestücktechniken geeignet
- **Lötmethode:** IR Reflow Löten und Wellenlöten (TTW)
- **Vorbehandlung:** nach JEDEC Level 2
- **Gurtung:** 8 mm Gurt mit 3000/Rolle, $\varnothing 180$ mm oder 10000/Rolle, $\varnothing 330$ mm
- **ESD-Festigkeit:** ESD-sicher bis 2 kV nach EOS/ESD-5.1-1993

Anwendungen

- Hinterleuchtung (LCD, Mobiltelefone, Schalter, Tasten, Displays, Werbebeleuchtung)
- optimierte Einkopplung in Lichtleiter
- Signal- und Symbolleuchten

Features

- **package:** white SMT package
- **feature of the device:** small package with extremely wide viewing angle; ideal for backlighting and coupling in light guides
- **color coordinates:** $x = 0.33$, $y = 0.33$ acc. to CIE 1931 (white)
- **typ. color temperature:** 5600 K
- **color reproduction index:** 80
- **viewing angle:** Lambertian Emitter (120°)
- **technology:** InGaN
- **optical efficiency:** 10 lm/W
- **grouping parameter:** luminous intensity, color coordinates
- **assembly methods:** suitable for all SMT assembly methods
- **soldering methods:** IR reflow soldering and TTW soldering
- **preconditioning:** acc. to JEDEC Level 2
- **taping:** 8 mm tape with 3000/reel, $\varnothing 180$ mm or 10000/reel, $\varnothing 330$ mm
- **ESD-withstand voltage:** up to 2 kV acc. to EOS/ESD-5.1-1993

Applications

- backlighting (LCD, mobile phones, switches, keys, displays, illuminated advertising)
- optimized coupling into light guides
- signal and symbol luminaire

Type	Emissions- farbe	Farbe der Lichtaustritts- fläche	Lichtstärke	Lichtstrom	Bestellnummer
Type	Color of Emission	Color of the Light Emitting Area	Luminous Intensity $I_F = 20 \text{ mA}$ $I_V \text{ (mcd)}$	Luminous Flux $I_F = 20 \text{ mA}$ $\Phi_V \text{ (lm)}$	Ordering Code
LW Y87C-S1T1-3C5D	white	colored	180 ... 355	800 (typ.)	Q65110A0573
LW Y87C-T1U1-3C5D		diffused	280 ... 560	1250 (typ.)	Q65110A0574
LW Y87C-S1T1-2C5D	white	colored	180 ... 355	800 (typ.)	on request
LW Y87C-T1U1-2C5D		diffused	280 ... 560	1250 (typ.)	on request

Anm.: -2C5D Farbselektiert nach Farbortgruppen (siehe **Seite 5**)

*Die Standardlieferform von Serientypen beinhaltet eine untere bzw. eine obere Familiengruppe, die aus nur 2 bzw. 3 Halbgruppen besteht. Einzelne Halbgruppen sind nicht erhältlich.
In einer Verpackungseinheit / Gurt ist immer nur eine Halbgruppe enthalten.*

Note: -2C5D Color selection acc. to Chromaticity coordinate groups (see **page 5**)

*The standard shipping format for serial types includes a lower or upper family group of 2 or 3 individual groups. Individual half groups are not available.
No packing unit / tape ever contains more than one luminous intensity half group.*

Grenzwerte
Maximum Ratings

Bezeichnung Parameter	Symbol Symbol	Wert Value	Einheit Unit
Betriebstemperatur Operating temperature range	T_{op}	– 40 ... + 100	°C
Lagertemperatur Storage temperature range	T_{stg}	– 40 ... + 100	°C
Sperrschichttemperatur Junction temperature	T_j	+ 110	°C
Durchlassstrom Forward current	I_F	20	mA
Stoßstrom Surge current $t \leq 10 \mu s, D = 0.005$	I_{FM}	300	mA
Sperrspannung ¹⁾ Reverse voltage	V_R	5	V
Leistungsaufnahme Power consumption $T_A \leq 25 \text{ °C}$	P_{tot}	85	mW
Wärmewiderstand Thermal resistance Sperrschicht/Umgebung Junction/ambient	$R_{th JA}$	600	K/W
Sperrschicht/Lötpad Junction/solder point Montage auf PC-Board FR 4 (Padgröße $\geq 5 \text{ mm}^2$) mounted on PC board FR 4 (pad size $\geq 5 \text{ mm}^2$)	$R_{th JS}$	350	K/W

¹⁾ für kurzzeitigen Betrieb geeignet / suitable for short term application

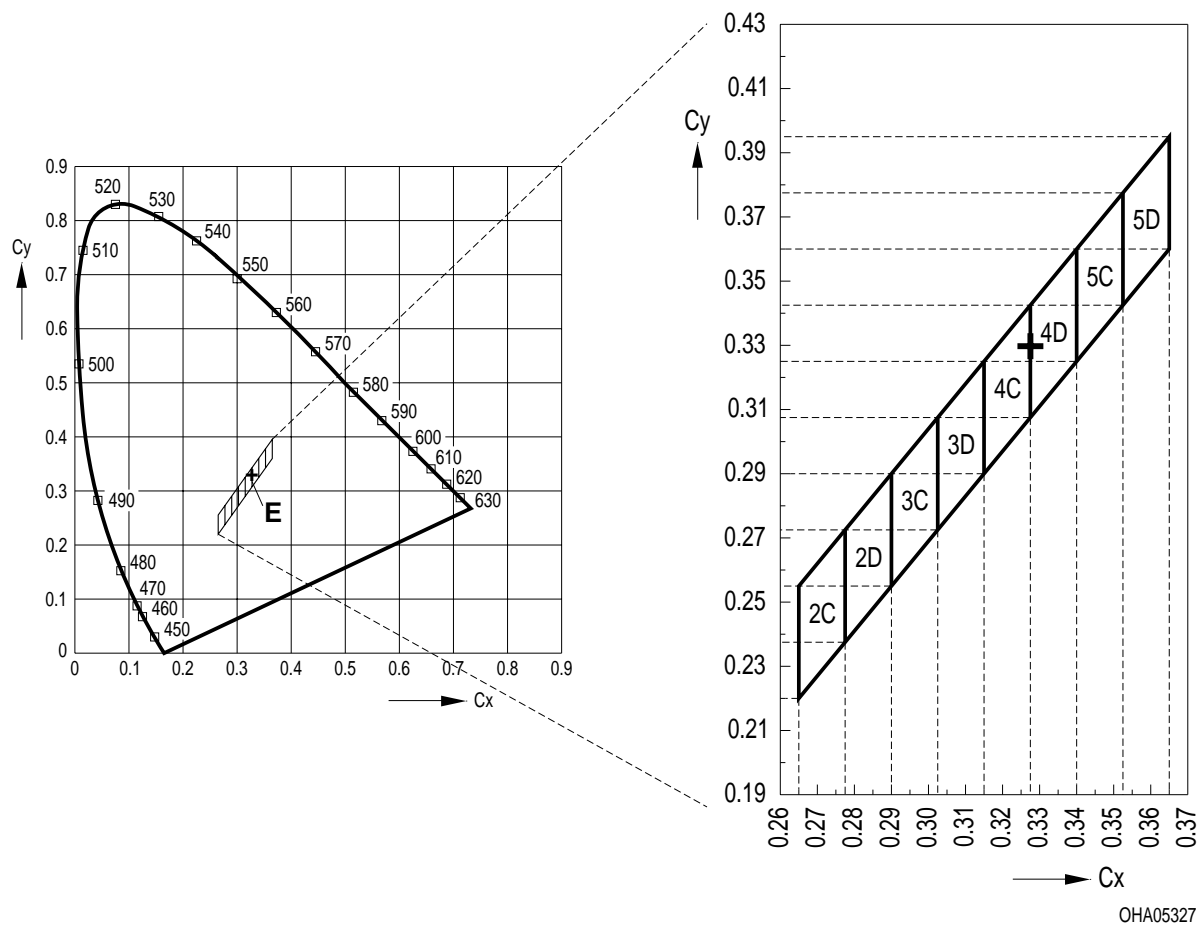
Kennwerte ($T_A = 25\text{ °C}$)**Characteristics**

Bezeichnung Parameter	Symbol Symbol	Wert Value	Einheit Unit
Farbkoordinate x nach CIE 1931 ¹⁾ (typ.) Chromaticity coordinate x acc. to CIE 1931 $I_F = 20\text{ mA}$	x	0.33	–
Farbkoordinate y nach CIE 1931 ¹⁾ (typ.) Chromaticity coordinate y acc. to CIE 1931 $I_F = 20\text{ mA}$	y	0.33	–
Abstrahlwinkel bei 50 % I_V (Vollwinkel) (typ.) Viewing angle at 50 % I_V	2φ	120	Grad deg.
Durchlassspannung ²⁾ (min.) Forward voltage (typ.) $I_F = 20\text{ mA}$ (max.)	V_F V_F V_F	3.0 3.6 4.1	V V V
Sperrstrom (typ.) Reverse current (max.) $V_R = 5\text{ V}$	I_R I_R	0.01 10	μA μA
Temperaturkoeffizient von x (typ.) Temperature coefficient of x $I_F = 20\text{ mA}; -10\text{ °C} \leq T \leq 100\text{ °C}$	TC_x	– 0.1	$10^{-3}/\text{K}$
Temperaturkoeffizient von y (typ.) Temperature coefficient of y $I_F = 20\text{ mA}; -10\text{ °C} \leq T \leq 100\text{ °C}$	TC_y	– 0.2	$10^{-3}/\text{K}$
Temperaturkoeffizient von V_F (typ.) Temperature coefficient of V_F $I_F = 20\text{ mA}; -10\text{ °C} \leq T \leq 100\text{ °C}$	TC_V	– 3.0	mV/K
Optischer Wirkungsgrad (typ.) Optical efficiency $I_F = 20\text{ mA}$	η_{opt}	10	lm/W

¹⁾ Farbortgruppen werden mit einer Stromeinprägедauer von 25 ms und einer Genauigkeit von $\pm 0,01$ ermittelt.
Chromaticity coordinate groups are tested at a current pulse duration of 25 ms and a tolerance of ± 0.01 .

²⁾ Durchlassspannungsgruppen werden mit einer Stromeinprägедauer von 1 ms und einer Genauigkeit von $\pm 0,05\text{ V}$ ermittelt.
Forward voltage groups are tested at a current pulse duration of 1 ms and a tolerance of $\pm 0.05\text{ V}$.

1) **Farbortgruppen**
Chromaticity coordinate groups



Helligkeits-Gruppierungsschema Luminous Intensity Groups

Lichtgruppe Luminous Intensity Group	Lichtstärke Luminous Intensity I_v (mcd)	Lichtstrom Luminous Flux Φ_v (lm)
S1	180 ... 224	600 (typ.)
S2	224 ... 280	760 (typ.)
T1	280 ... 355	950 (typ.)
T2	355 ... 450	1200 (typ.)
U1	450 ... 560	1500 (typ.)
U2	560 ... 710	1900 (typ.)

Helligkeitswerte werden mit einer Stromeinprägedauer von 25 ms und einer Genauigkeit von $\pm 11\%$ ermittelt.
Luminous intensity is tested at a current pulse duration of 25 ms and a tolerance of $\pm 11\%$.

Gruppenbezeichnung auf Etikett

Group Name on Label

Beispiel: S2-4D

Example: S2-4D

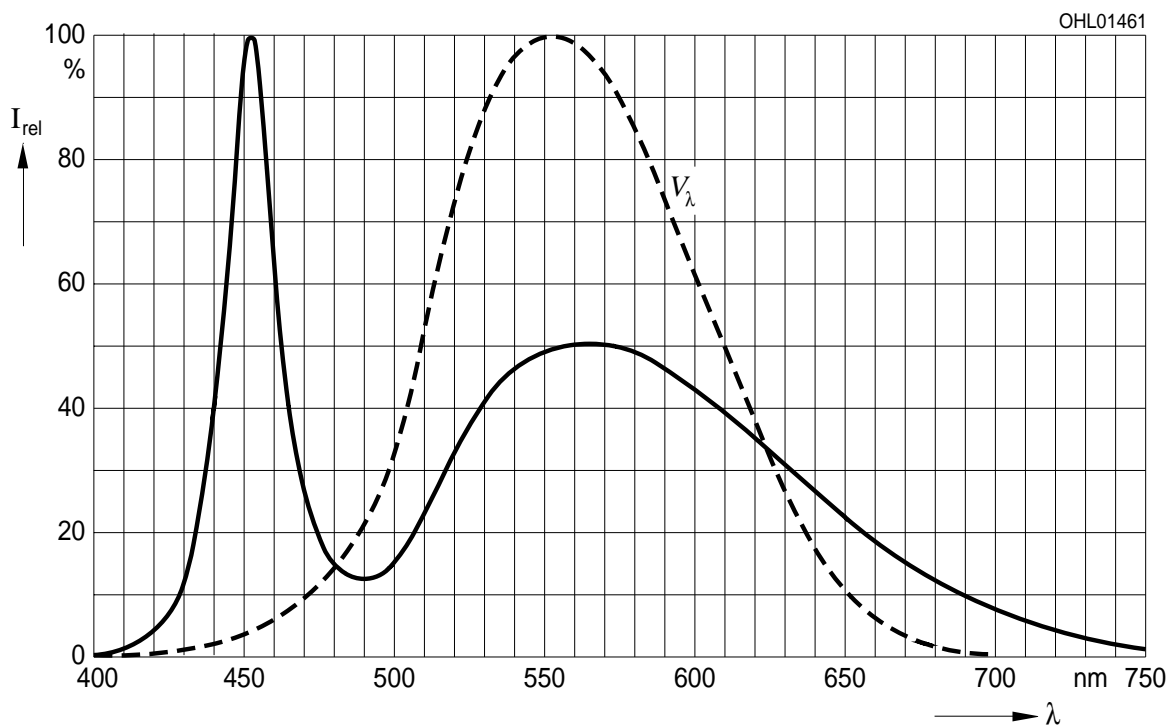
Lichtgruppe Luminous Intensity Group	Halbgruppe Half Group	Farbortgruppe Chromaticity Coordinate Group
S	2	4D

Relative spektrale Emission $I_{\text{rel}} = f(\lambda)$, $T_A = 25^\circ\text{C}$, $I_F = 20\text{ mA}$

Relative Spectral Emission

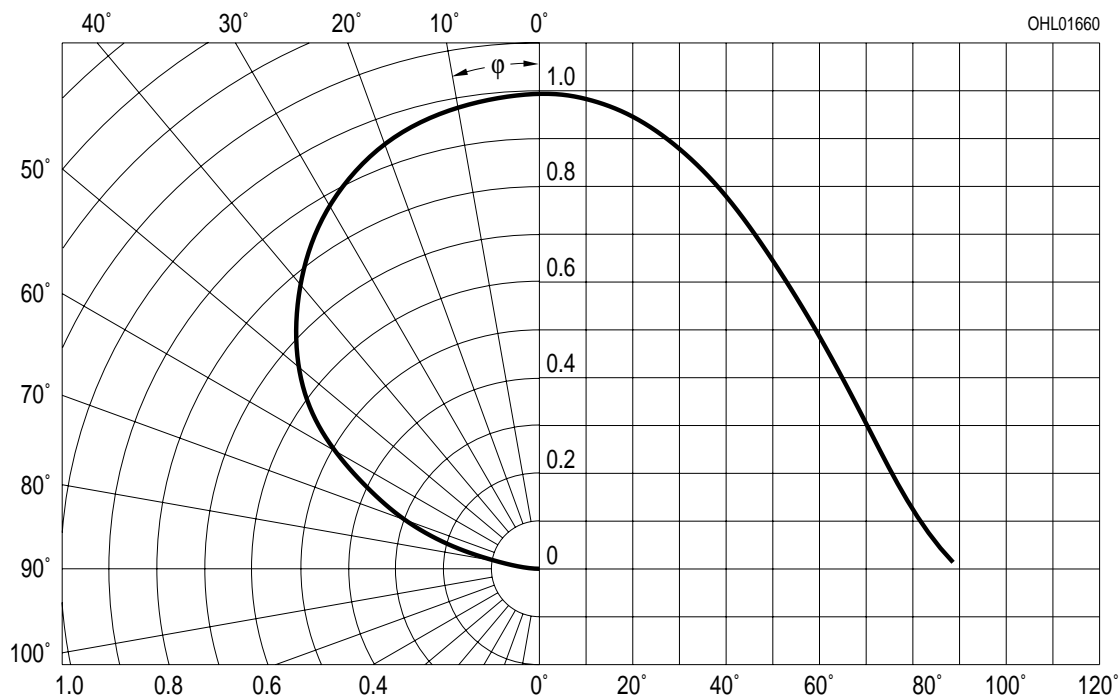
$V(\lambda)$ = spektrale Augenempfindlichkeit

Standard eye response curve



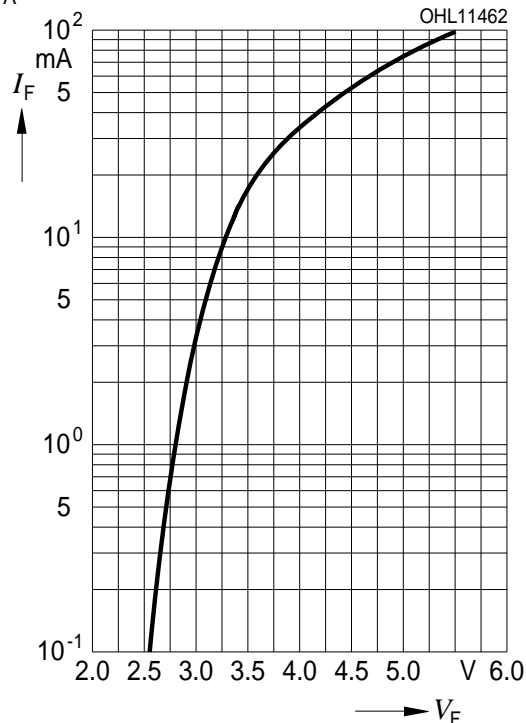
Abstrahlcharakteristik $I_{\text{rel}} = f(\varphi)$

Radiation Characteristic

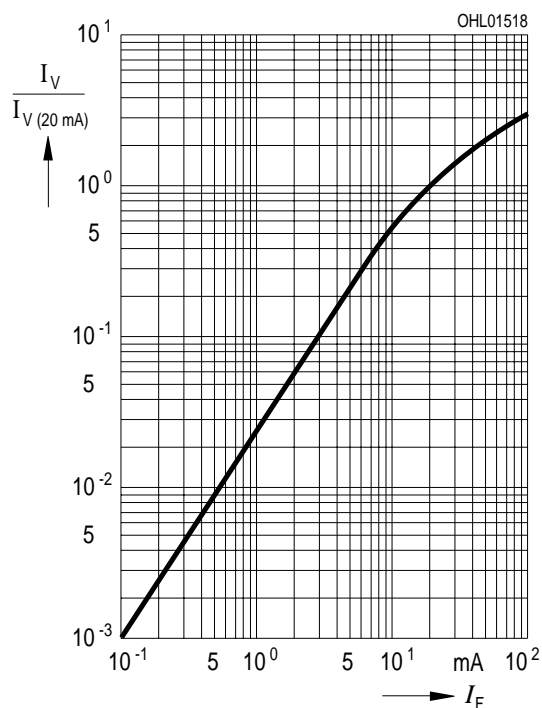


Durchlassstrom $I_F = f(V_F)$

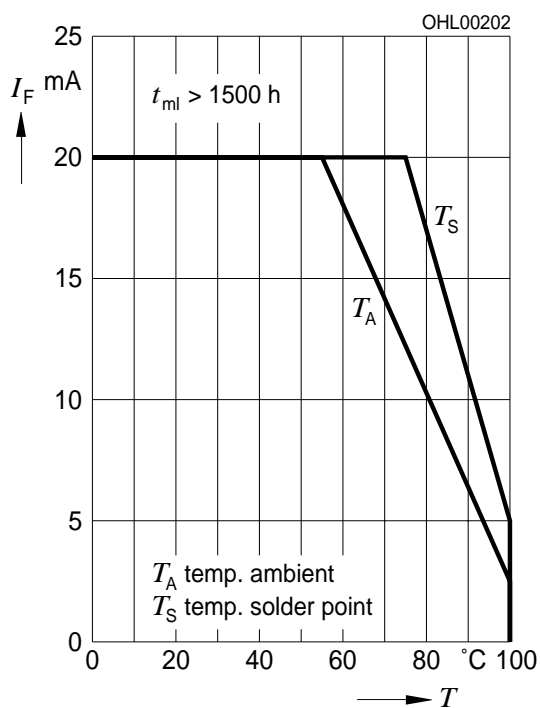
Forward Current

 $T_A = 25\text{ °C}$ Relative Lichtstärke $I_V/I_{V(20\text{ mA})} = f(I_F)$

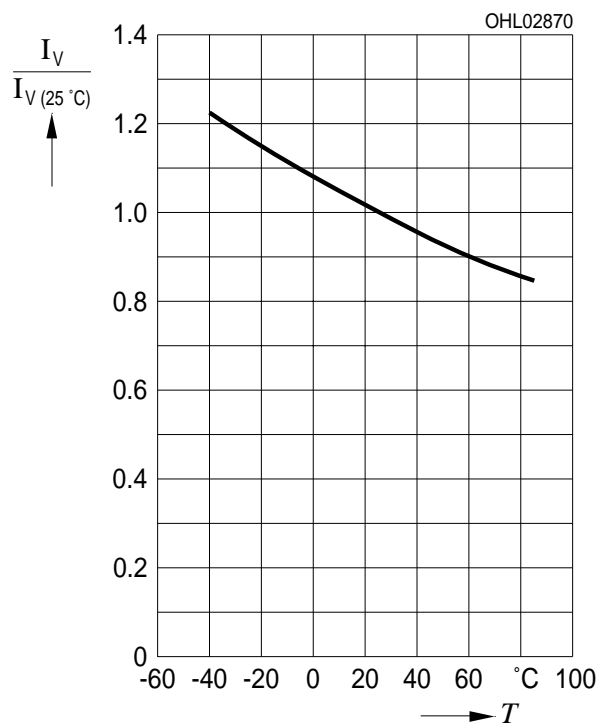
Relative Luminous Intensity

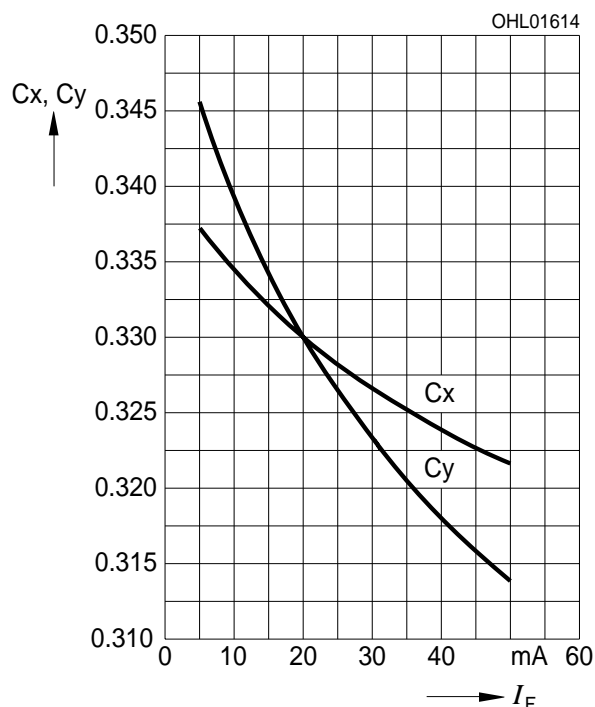
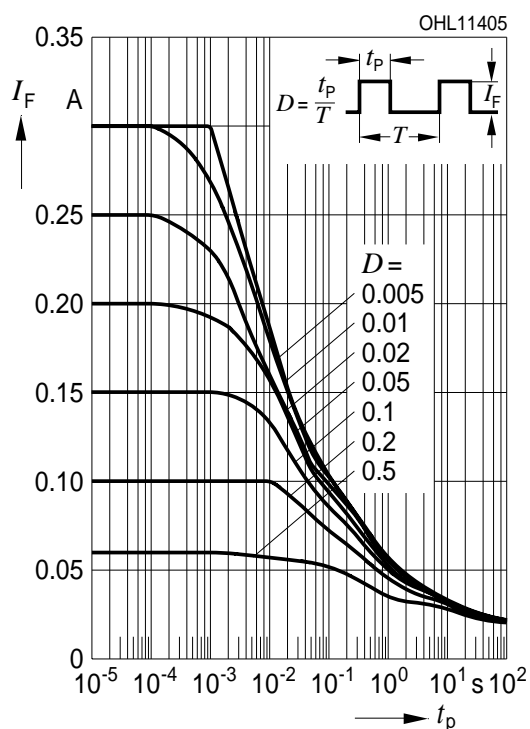
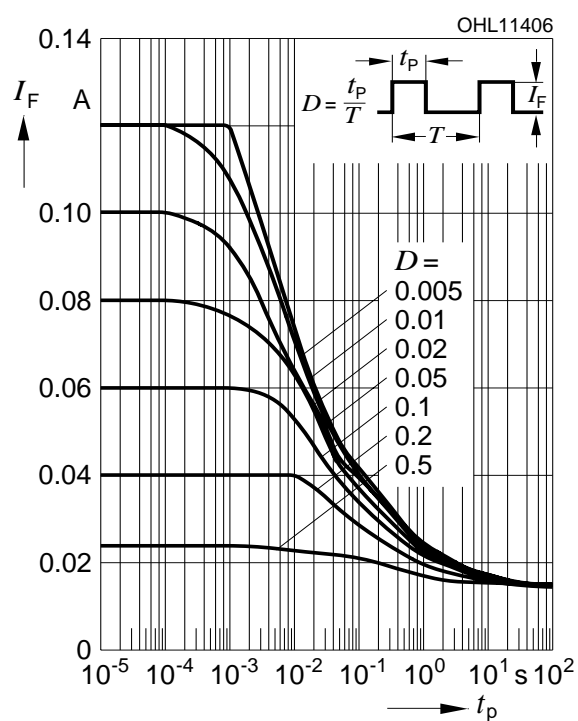
 $T_A = 25\text{ °C}$ Maximal zulässiger Durchlassstrom $I_F = f(T)$

Max. Permissible Forward Current

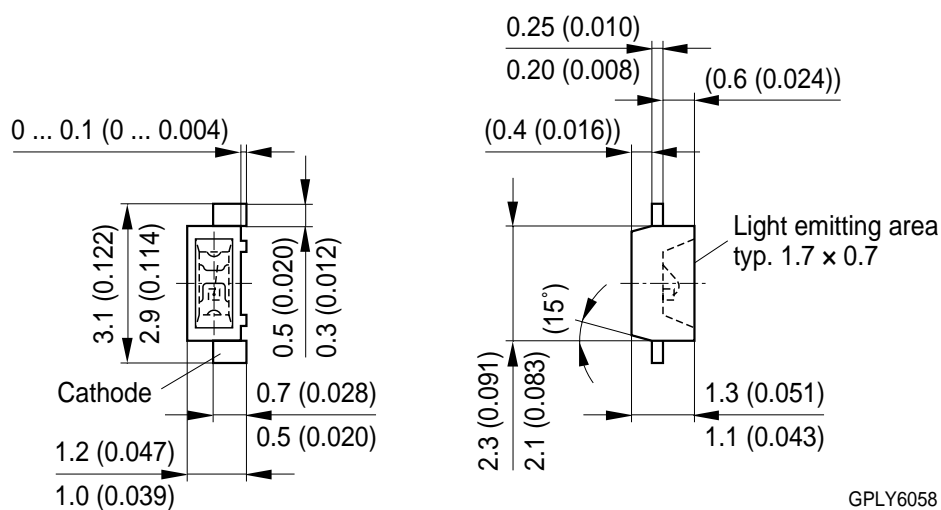
Relative Lichtstärke $I_V/I_{V(25\text{ °C})} = f(T_A)$

Relative Luminous Intensity

 $I_F = 20\text{ mA}$ 

Farbortverschiebung $x, y = f(I_F)$ **Chromaticity Coordinate Shift** $T_A = 25\text{ °C}$ **Zulässige Impulsbelastbarkeit $I_F = f(t_p)$** **Permissible Pulse Handling Capability**Duty cycle $D = \text{parameter}$, $T_A = 25\text{ °C}$ **Zulässige Impulsbelastbarkeit $I_F = f(t_p)$** **Permissible Pulse Handling Capability**Duty cycle $D = \text{parameter}$, $T_A = 85\text{ °C}$ 

Maßzeichnung Package Outlines

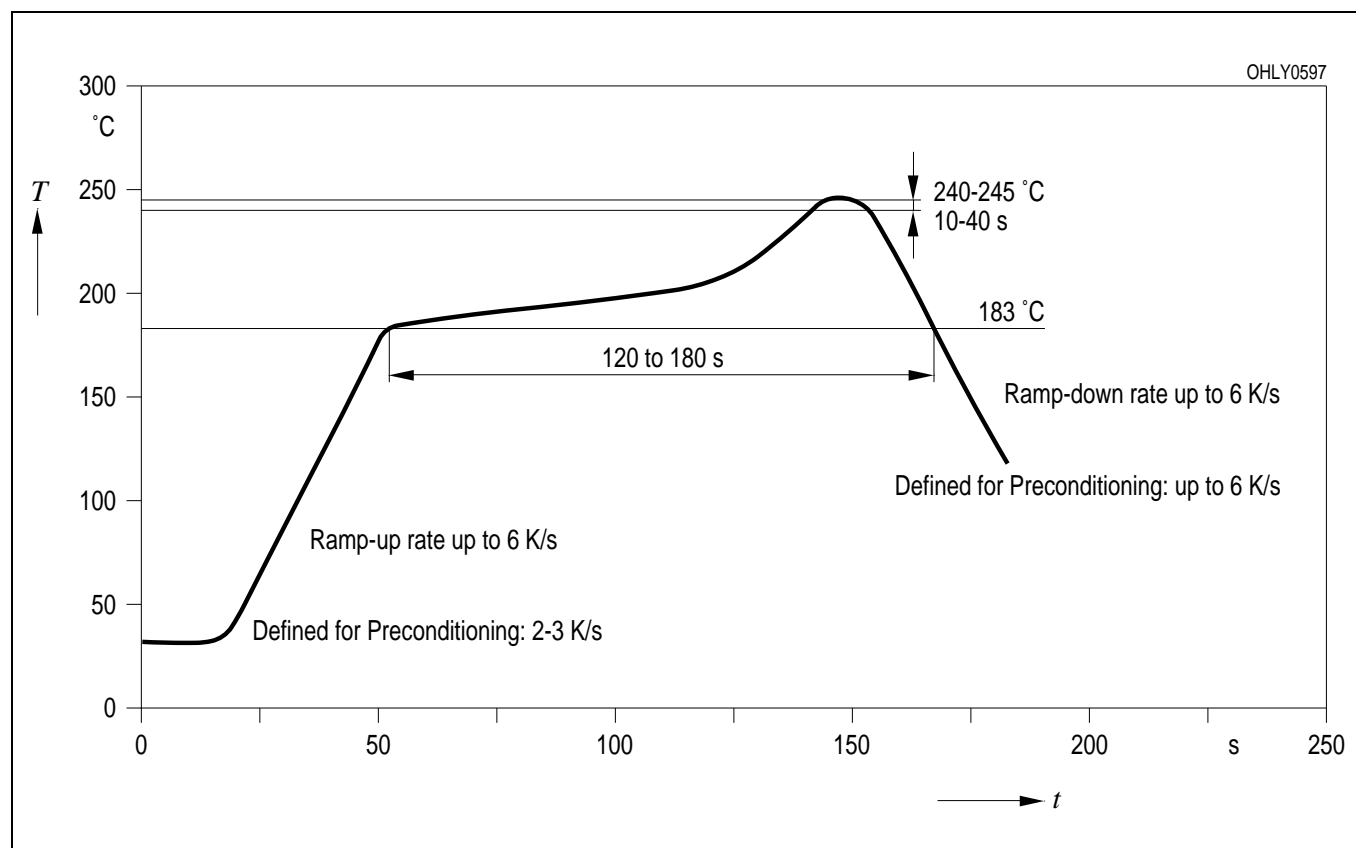


Maße werden wie folgt angegeben: mm (inch) / Dimensions are specified as follows: mm (inch).

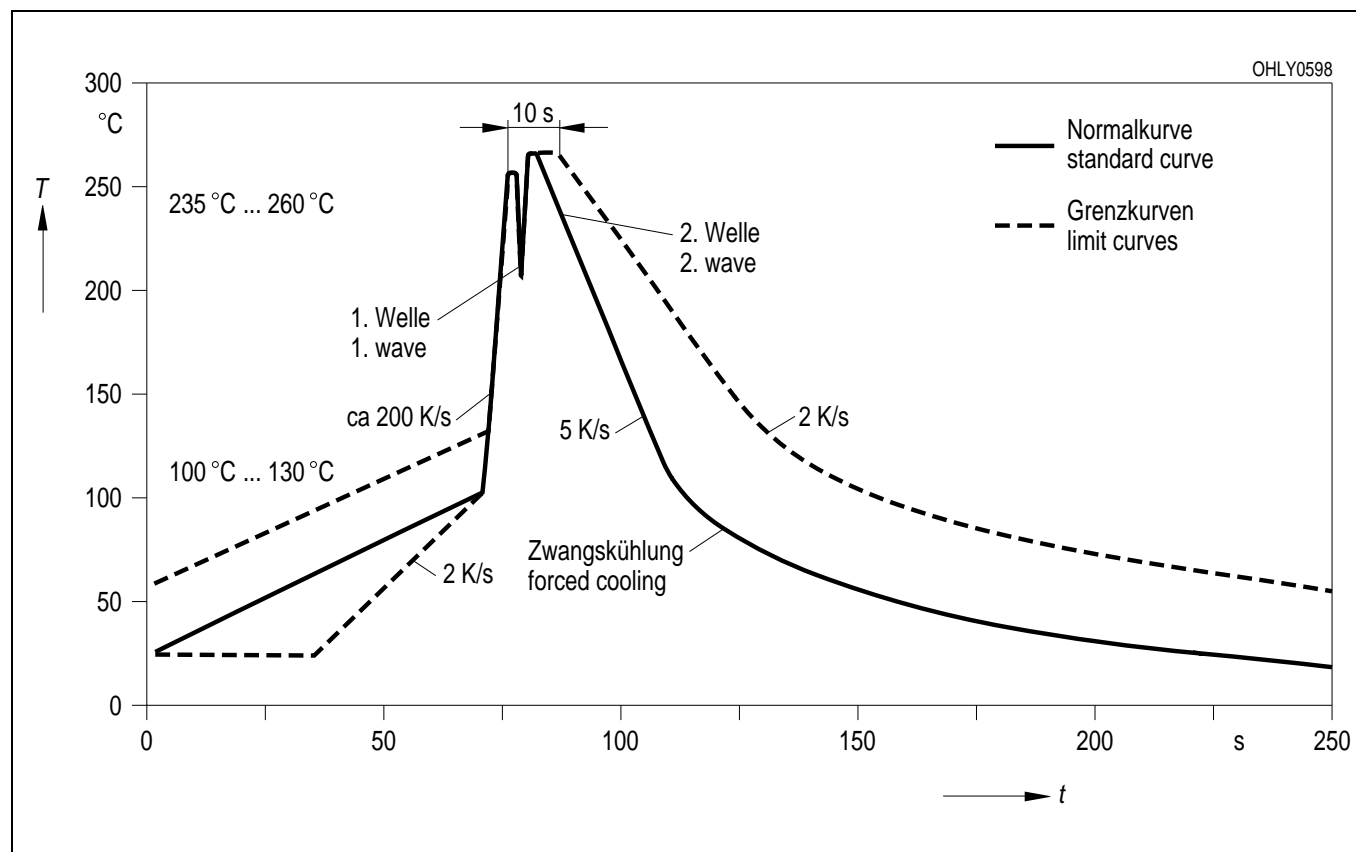
Gewicht / Approx. weight: 6 mg

Lötbedingungen Vorbehandlung nach JEDEC Level 2
Soldering Conditions Preconditioning acc. to JEDEC Level 2

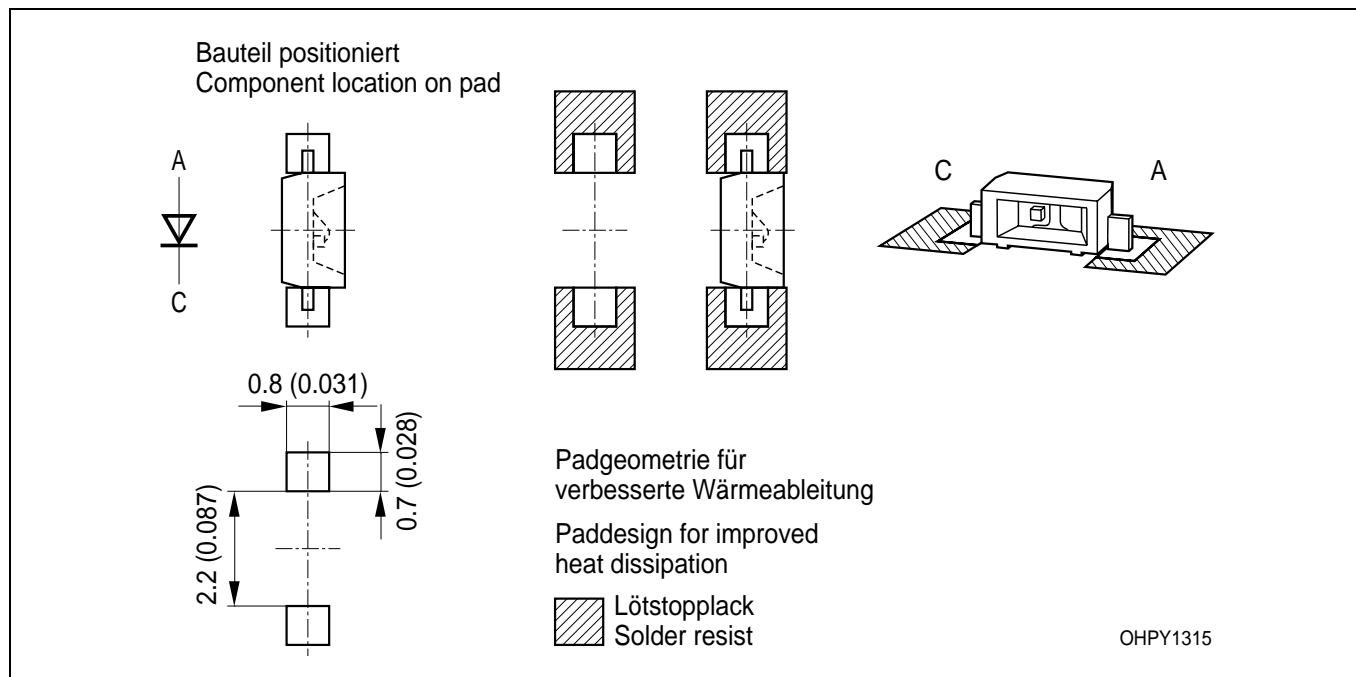
IR-Reflow Lötprofil (nach IPC 9501)
IR Reflow Soldering Profile (acc. to IPC 9501)



Wellenlöten (TTW) (nach CECC 00802)
TTW Soldering (acc. to CECC 00802)



Empfohlenes Lötpaddesign IR Reflow Lötén
Recommended Solder Pad IR Reflow Soldering



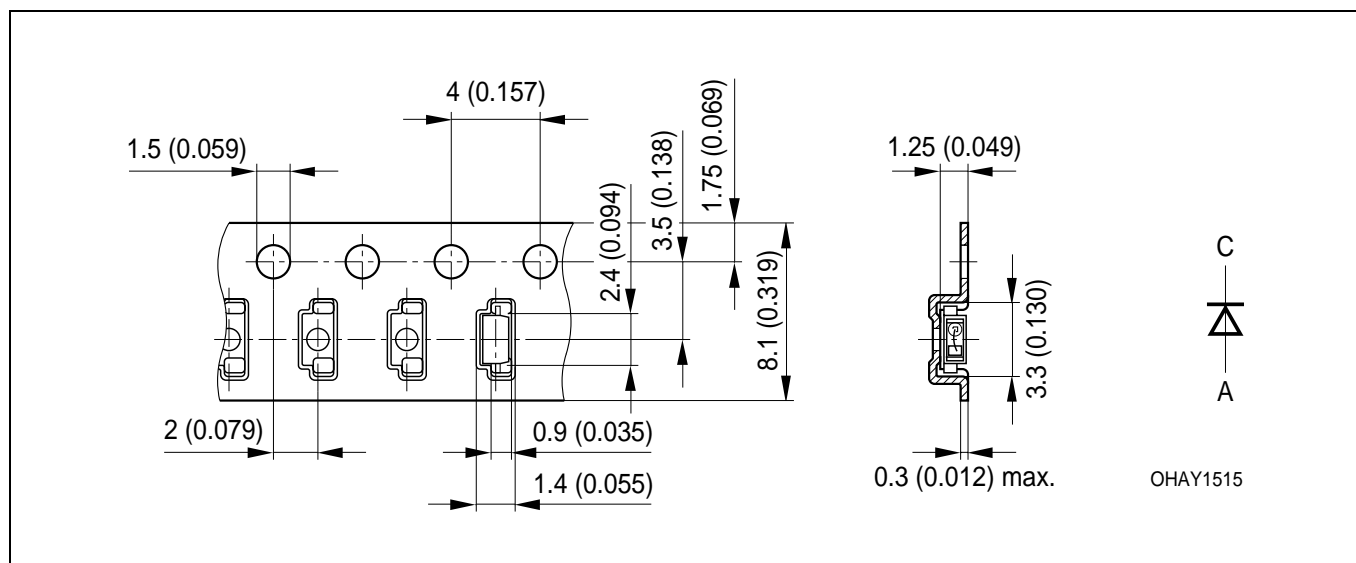
Maße werden wie folgt angegeben: mm (inch) / Dimensions are specified as follows: mm (inch).
 Gehäuse hält TTW-Löthitze aus / Package able to withstand TTW-soldering heat

Gurtung / Polarität und Lage

Verpackungseinheit 3000/Rolle, ø180 mm
 oder 10000/Rolle, ø330 mm

Method of Taping / Polarity and Orientation

Packing unit 3000/reel, ø180 mm
 or 10000/reel, ø330 mm



Maße werden wie folgt angegeben: mm (inch) / Dimensions are specified as follows: mm (inch).

Revision History: 2003-03-04		Date of change
Previous Version: 2002-11-18		
Page	Subjects (major changes since last revision)	
2	luminous intensity grouping	
4	optical efficiency	
4	forward voltage	
8	max. permissible forward current	
3	power consumption from 90 mW to 85 mW	
8	diagram luminous intensity from OHL01462 to OHL11462	
8	diagram relative luminous intensity OHL01637 to OHL02870	
9	new diagrams OHL11405 and OHL11406 (permissible pulse handling capability)	
2	wavelength grouping for white	
3	surge current from t.b.d. to 300mA	
3	pad size from 16 mm ² to 5 mm ²	
14	annotations	2002-07-25
3	reverse voltage (footnote)	2002-08-21
2, 5	new luminous intensity groups and new ordering codes	2002-10-25
2, 5	Chromaticity coordinate groups	2002-11-18
14	new patent no.	2003-03-04

Patent List

Patent No.

US 6 066 861, US 6 277 301, US 6 245 259

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Attention please!

The information describes the type of component and shall not be considered as assured characteristics.

All typical data and graphs are basing on representative samples, but don't represent the production range. If requested, e.g. because of technical improvements, these typ. data will be changed without any further notice.

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Packing

Please use the recycling operators known to you. We can also help you – get in touch with your nearest sales office. By agreement we will take packing material back, if it is sorted. You must bear the costs of transport. For packing material that is returned to us unsorted or which we are not obliged to accept, we shall have to invoice you for any costs incurred.

Components used in life-support devices or systems must be expressly authorized for such purpose! Critical components ¹ may only be used in life-support devices or systems ² with the express written approval of OSRAM OS.

¹ A critical component is a component used in a life-support device or system whose failure can reasonably be expected to cause the failure of that life-support device or system, or to affect its safety or the effectiveness of that device or system.

² Life support devices or systems are intended (a) to be implanted in the human body, or (b) to support and/or maintain and sustain human life. If they fail, it is reasonable to assume that the health of the user may be endangered.